PCN Number:		20201	201000.	1		P	CN D	ate	:	Jan. 1	1, 2021	
Title: Quali	of MIHO	HO8 as an additional Fab site option for select devices										
Customer Conta										Quality Services		
					E	stimate	-	mpl	e	-	provided at	
Proposed 1 st Ship Date:			pr. 11, 2	2021		vailabi				•	e request.	
Change Type:											I I	
Assembly Si		Asse	mbly Pro	cess		Assem				mbly Materials		
Design			Elect	rical Spe	ecificatio				Mechanical Specificati			ion
Test Site			Packing/Shipping			'Labeling			Test Process			
Wafer Bump		Wafer Bump Material						Wafer Bump Process				
🛛 🛛 Wafer Fab S			r Fab Ma					Wafer Fab Process				
			Part	number								
				PCN I	Detail	S						
Description of C												
Texas Instrument additional Wafer	Fab sour	rce for t	he select			d in the	"Proc	luct	Affe	cted" s		1
C	urrent F	ab Site				A	dditi	ona	l Fal	o Site		
Current Fab Site	Proc	Process		fer eter	Addit Fab		P	Process		Wafer Diameter		
MAINEFAB	ABCD	ABCD5HV		mm	MIH		A	3CD	5HV			
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Qualification Report

Approve Date 13-Oct-2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: <u>ISO1042QDWQ1</u>	QBS Product Reference: <u>ISO1042DW</u> (PG1.1)	QBS Product Reference: ISO1042DW(PG1.0)	QBS Process Reference: ISO7741FQDWQ1	QBS Process Reference: <u>TCAN1042HVDRQ1</u> (PG 2.0).	QBS Package Reference: <u>ISO1042DW</u> <u>(PG1.1)</u>	QBS Package Reference: ISO1042DW(PG1.0)
AC	Autoclave 121C	96 Hours	-	1/77/0	2/154/0	3/231/0	3/231/0	1/77/0	2/154/0
CDM	ESD - CDM	1500 V	-	1/3/0	-	-	-	-	-
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	-	-	-	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	-	3/2400/0	3/2400/0	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	1/77/0	3/231/0	3/231/0	-	1/77/0
HBM	ESD - HBM (All Pins)	8000 V	-	1/3/0	-	-	-	-	-
HBM	ESD - HBM (Bus Pins Only)	16000 V	-	1/3/0	-	-	-	-	-
HTOL	Life Test, 125C	1000 Hours	-	1/77/0	2/154/0	3/231/0	-	1/77/0	2/154/0
HTOL	Life Test, 150C	300 Hours	-	-	-	-	3/231/0	-	-
HTSL	High Temp Storage Bake 150C	1000 Hours	-	1/77/0	2/154/0	-	3/135/0	1/77/0	2/154/0
HTSL	High Temp Storage Bake 175C	500 Hours	-	-	-	3/231/0	-	-	-
LU	Latch-up	(Per JESD78)	-	1/6/0	-	-	-	-	-
тс	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	-	3/231/0	3/231/0	3/231/0	-
WBP	Bond Pull	Wires	1/76/0	3/182/0	-	3/228/0	3/228/0	3/182/0	-
WBS	Bond Shear	Wires	1/76/0	3/182/0	-	3/228/0	3/228/0	3/182/0	-

- QBS: Qual By Similarity

- Qual Device ISO1042QDWQ1 is qualified at LEVEL3-260C

- Device ISO1042QDWQ1 contains multiple dies.

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

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